



Material Content Data Sheet



Sales Product Name	BSC110N06NS3 G			Issued		11. December 2019		
MA#	MA001510240							
Package	PG-TDSON-8-40			Weight*		111.97 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.296	1.16	1.16	11574	11574
leadframe	inorganic material	phosphorus	7723-14-0	0.015	0.01		131	
	non noble metal	iron	7439-89-6	0.049	0.04		435	
	non noble metal	copper	7440-50-8	48.649	43.46	43.51	434475	435041
wire	non noble metal	copper	7440-50-8	0.060	0.05	0.05	536	536
encapsulation	organic material	carbon black	1333-86-4	0.084	0.07		747	
	plastics	epoxy resin	-	6.608	5.90		59016	
	inorganic material	silicondioxide	60676-86-0	35.132	31.38	37.35	313754	373517
leadfinish	non noble metal	tin	7440-31-5	1.520	1.36	1.36	13575	13575
plating	noble metal	silver	7440-22-4	0.158	0.14	0.14	1415	1415
solder	non noble metal	tin	7440-31-5	0.029	0.03		263	
	noble metal	silver	7440-22-4	0.037	0.03		328	
	non noble metal	lead	7439-92-1	1.404	1.25	1.31	12535	13126
heat sink clip	inorganic material	phosphorus	7723-14-0	0.005	0.00		45	
	non noble metal	iron	7439-89-6	0.017	0.02		151	
	non noble metal	copper	7440-50-8	16.910	15.10	15.12	151020	151216
*deviation	< 10%				Sum in total:		100.00	1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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